

NCTU-EE IC Design LAB – Spring2022

Lab11 Exercise: Innovus - From RTL to GDSII

In this exercise, you are going to perform the APR steps to the design : local binary pattern

1. Data Preparation

1. Complete rtl simulation, synthesis, and gate level simulation.(Done by TA)
2. Change the directory to **05_APR**
3. Prepare chip design netlist:
 - a. Open **CHIP_SHELL.v**
 - The top module name is **CHIP**.
 - This **CHIP** contains the module **LBP**, and **I/O**, **I/O power**, **core power** pad.
 - Please calculate how many I/O and core power pads you need, and **complete the netlist of pad cells** (size and action).
 - After defining the pad cells, please run **%./00_combine** to combine the LBP_SYN.v with CHIP_SHELL.v to be CHIP_SYN.v
4. Prepare I/O pad location file:
 - a. Please see **Appendix A** to know how to assign I/O pad location.
 - b. Open **CHIP.io** and complete the I/O pad location assignment according to the netlist of pad cells in **CHIP_SYN.v** (size and action).
- ✓5. Prepare timing/driving/loading constraint file **CHIP.sdc**:
 - a. Copy it from the synthesis result:
 - **cp ../02_SYN/Netlist/LBP_SYN.sdc CHIP.sdc** (Done by TA)
 - Modify the contents to the desired constraint
- ✓6. Prepare linked library files:
 - a. **Timing libraries (LIB)**
 - **slow.lib, fast.lib**
 - **umc18io3v5v_slow.lib, umc18io3v5v_fast.lib**
 - **RA1SH1_slow_syn.lib, RA1SH1_fast_syn.lib**
 - b. **Physical libraries (LEF)**
 - **umc18_6lm.lef**
 - **umc18_6lm_antenna.lef**
 - **umc18io3v5v_6lm.lef**
 - **RA1SH1.vclef**
 - c. **RC extraction table/files**
 - **umc18_1p6m.captbl**
 - **RCGen.tch**
 - d. **CeltIC libraries**
 - **slow.cdb, fast.cdb**
 - e. **GDSII layout** (Will not stream out in this course)
 - **umc18.gds2**
 - **umc18io3v5v_6lm.gds2**

➤ **RA1SH1.gds2** (not provided in this compiler version)

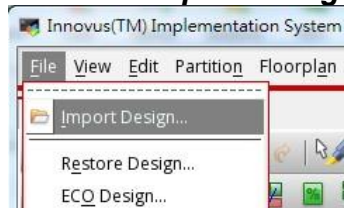
2. Reading Cell Library information and Netlist for APR

1. Start Innovus in the directory **05_APR**
% innovus (no &, do NOT use background execution)
2. Set uniquify global variable to 1
% set init_design_uniquify 1
3. Change design mode to 0.18um process
% setDesignMode -process 180
4. Skip error messages like the following figure when reading lef files
% suppressMessage TECHLIB 1318

```
**ERROR: (TECHLIB-1318): All the table values in the 'rise_transition' group are within '0.000010' of each other. (File /home/RAID2/COURSE/iclab/iclabta01/umc018/Lib/umc18io3v5v_slow.lib, Line 682)
**ERROR: (TECHLIB-1318): All the table values in the 'fall_transition' group are within '0.000010' of each other. (File /home/RAID2/COURSE/iclab/iclabta01/umc018/Lib/umc18io3v5v_slow.lib, Line 690)
**ERROR: (TECHLIB-1318): All the table values in the 'rise_transition' group are within '0.000010' of each other. (File /home/RAID2/COURSE/iclab/iclabta01/umc018/Lib/umc18io3v5v_slow.lib, Line 782)
```

This error message occurs since innovus assumes the values of rise / fall transition time should differ larger than 0.00001 ns in **the table** depending on the supply Voltage or the Temperature in **.lef file**. The error message can be ignored if the given .lef file is ensured to be correct. (Note: only suppress error when the reason is clearly verified instead of suppressing all errors)

5. In innovus menu, open **File → Import Design**



6. Fill the following field:
 - a. Netlist
 - ◆ Verilog
 - Files: **CHIP_SYN.v**
 - Top Cell: ◆ By User : **CHIP**
 - b. Technology / Physical Libraries
 - LEF Files: **umc18_6lm.lef umc18_6lm_antenna.lef umc18io3v5v_6lm.lef RA1SH.vclef**

Note that (1) the standard cell lef file should be put in the first place since it contains the major metals / vias / polys technology definitions. Also (2) if there are antenna lef files, they should be put after the corresponded lef files without describing antenna layers. For example: umc18_6lm.lef should be put in the first place; umc18_6lm_antenna.lef should be put after umc18_6lm.lef.

- c. Floorplan
 - IO Assignment Files: **CHIP.io**
- d. Power
 - Power Nets: **VDD**
 - Ground Nets: **GND**
- e. Analysis Configuration
 - Press “Create Analysis Configuration” tab

- Double click **Library Sets** and include the max and min delay library :

Max delay:

Name: lib_max

Timing Library: slow.lib, umc18io3v5v_slow.lib,
RA1SH_slow_syn.lib

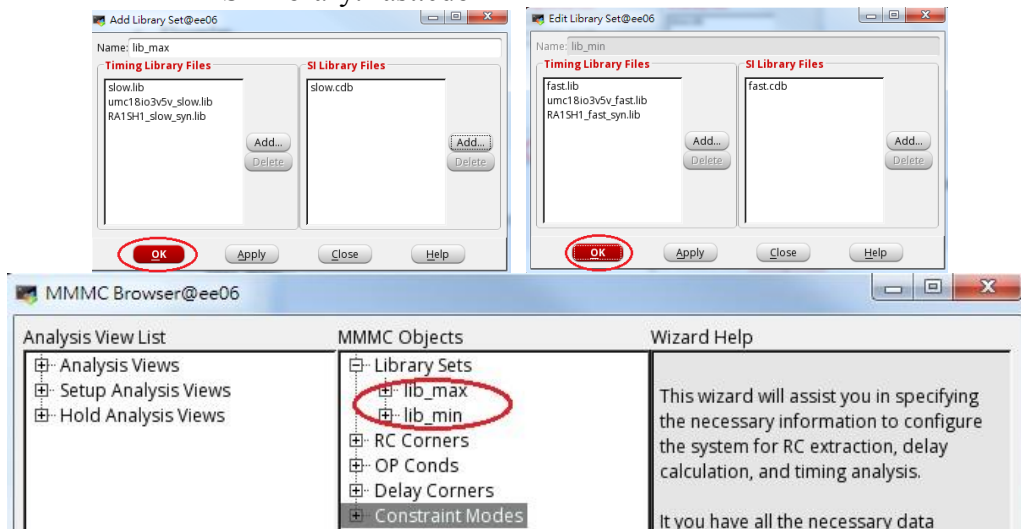
SI Library: slow.cdb

Min delay:

Name: lib_min

Timing Library: fast.lib, umc18io3v5v_fast.lib,
RA1SH_fast_syn.lib

SI Library: fast.cdb

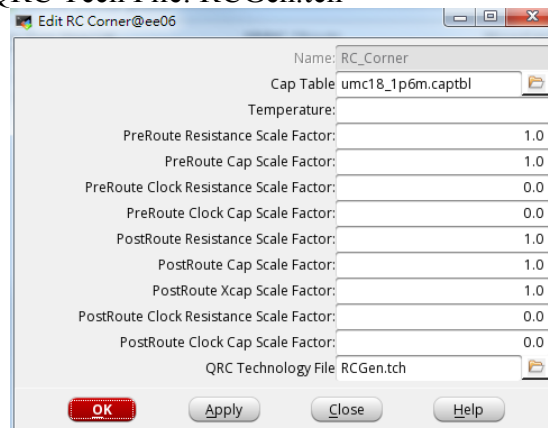


- Double click **RC Corners** to include the RC corner library :

Name: RC_Corner

Cap Table: umc18_1p6m.captbl

QRC Tech File: RCGen.tch



- Double click **Delay Corners** and create max and min delay constraints :

Max delay:

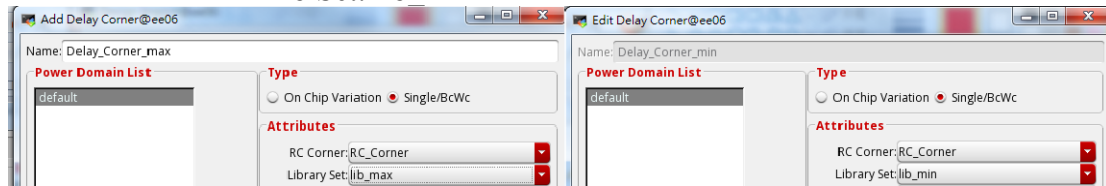
Name: Delay_Corner_max

RC Corner: RC_Corner

Lib Set: lib_max

Min delay:

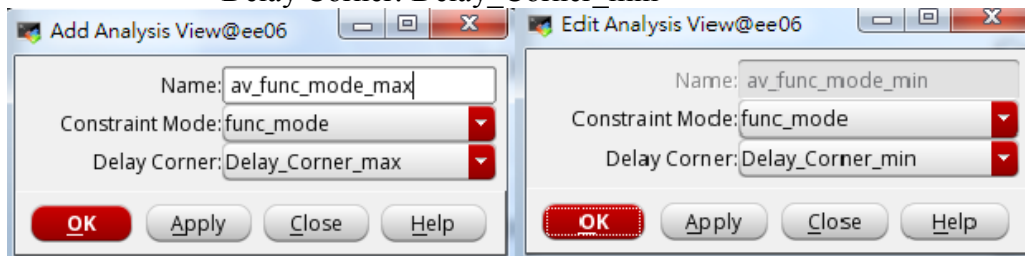
Name: Delay_Corner_min
 RC Corner: RC_Corner
 Lib Set: lib_min



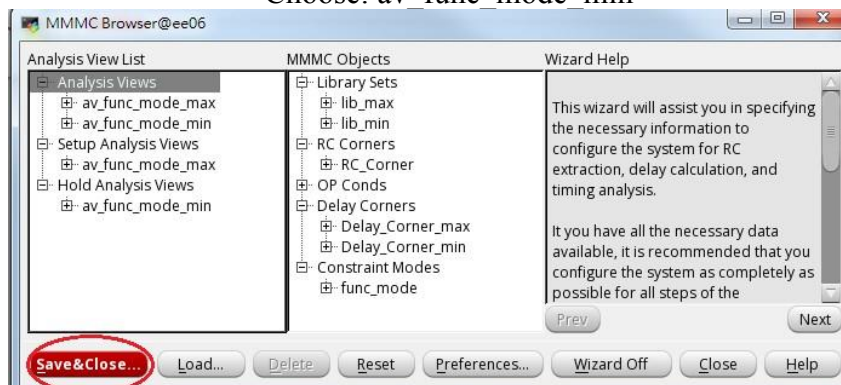
- Double click **Constraints Mode** and create a function mode to place CHIP_SYC.sdc :
 Name: func_mode
 SDC Constraint Files: CHIP.sdc



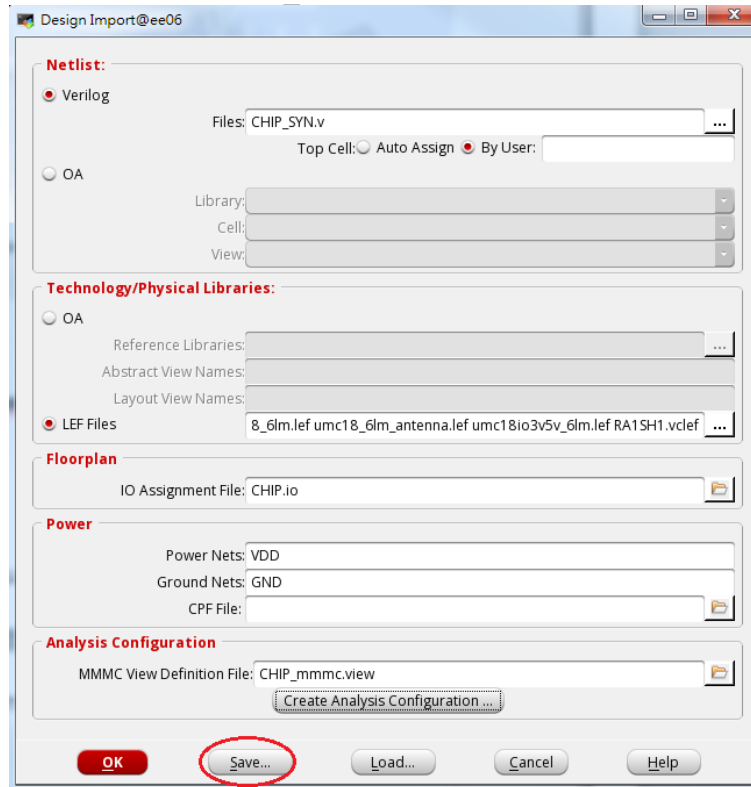
- Double click **Analysis Views** to create max and min delay analysis
Max delay:
 Name: av_func_mode_max
 Constraint Mode: func_mode
 Delay Corner: Delay_Corner_max
Min delay:
 Name: av_func_mode_min
 Constraint Mode: func_mode
 Delay Corner: Delay_Corner_min



- Click **Setup Analysis View** and specify the max analysis mode
 Choose: av_func_mode_max
- Click **Hold Analysis View** and specify the min analysis mode
 Choose: av_func_mode_min



➤ Save as “CHIP_mmmc.view”



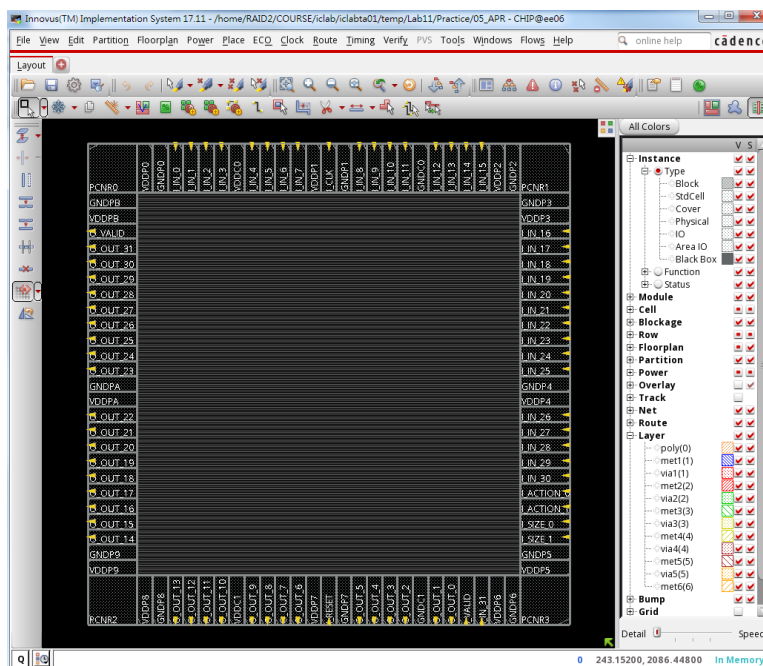
7. Save current settings:

a. Click **Save...** button

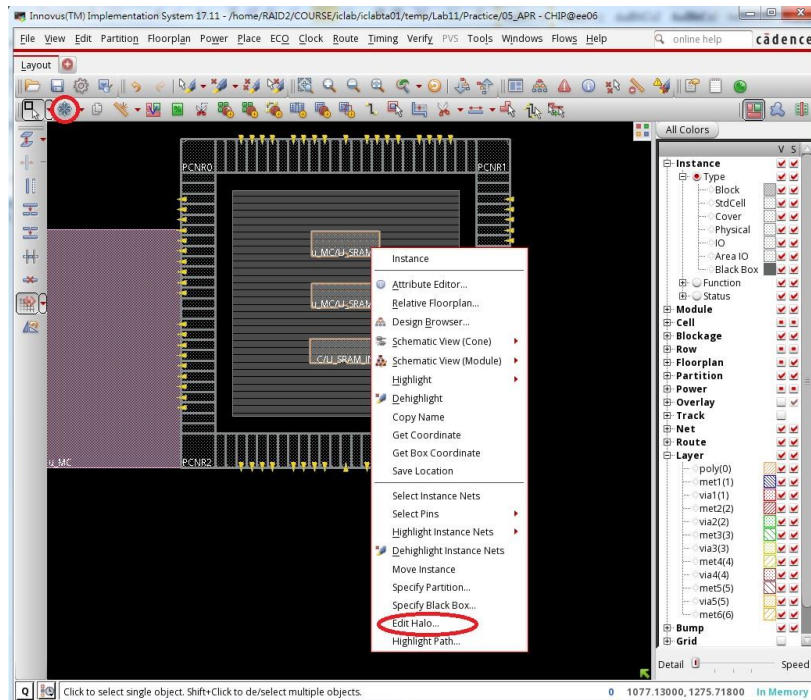
➤ File name: **CHIP.globals**

If you want to reload the settings, you can just press Load... button

8. Click **OK** button



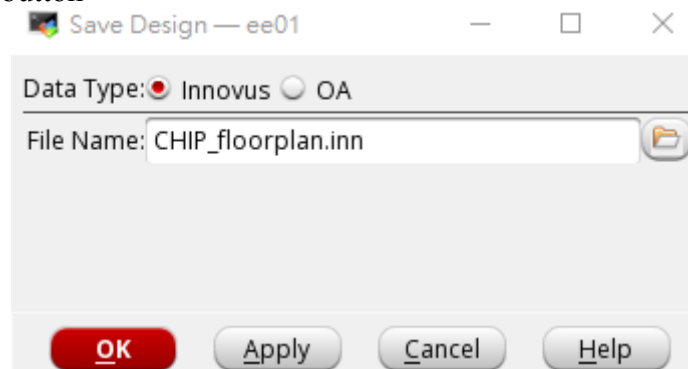
3. Specify Chip Floorplan



7. Specify Halo For: ♦ All Macros
Add/Update Halo: Top, Bottom, Left, Right: 15um
8. You can also create the placement blockage yourself with the button:



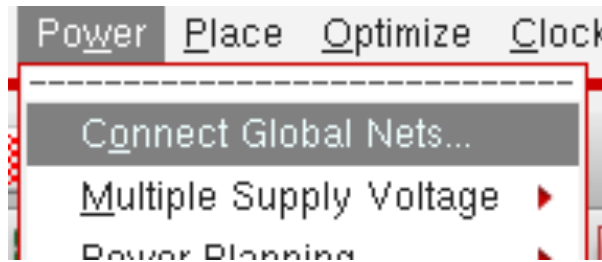
9. Save the floorplan design:
 - a. File → Save Design
 - b. Data Type ♦ Innovus
- File Name: CHIP_floorplan.inn
- c. Click OK button



If you do the wrong things in the following steps such as power planning, you can restore the design from the previous steps. However if the input files such as verilog file / io file / timing constraints are changed, you have to rerun all the APR steps.

4. Connect/Define Global Net

1. In innovus menu, open **Power** → **Connect Global Nets...**



2. Add all VDD pins to Connection List:
 - a. Connect ♦ Pin
Instance Basename: *
Pin Name(s): **VDD**
 - b. Scope ♦ Apply All
 - c. To Global Nets: VDD
 - d. Click Add to List button
3. Add all VDD nets to Connection List:
 - a. Connect ♦ Net Basename: **VDD**
 - b. Scope ♦ Apply All
 - c. To Global Nets: VDD
 - d. Click Add to List button
4. Add all Tie High pins to Connection List:
 - a. Connect ♦ Tie High
 - b. Scope ♦ Apply All
 - c. To Global Nets: VDD
 - d. Click Add to List button
5. Add all GND pins to Connection List:
 - a. Connect ♦ Pin
Instance Basename: *
Pin Name(s): **GND**
 - b. Scope ♦ Apply All
 - c. To Global Nets: GND
 - d. Click Add to List button
6. Add all GND nets to Connection List:
 - a. Connect ♦ Net Basename: **GND**
 - b. Scope ♦ Apply All
 - c. To Global Nets: GND
 - d. Click Add to List button
7. Add all Tie Low pins to Connection List:
 - a. Connect ♦ Tie Low
 - b. Scope ♦ Apply All
 - c. To Global Nets: GND
 - d. Click Add to List button
8. Add all VSS pins to Connection List: (For Macros)
 - a. Connect ♦ Pin
Instance Basename: *
Pin Name(s): **VSS**
 - b. Scope ♦ Apply All
 - c. To Global Nets: GND

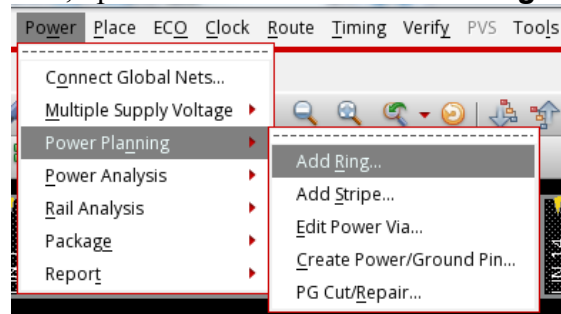
- d. Click Add to List button



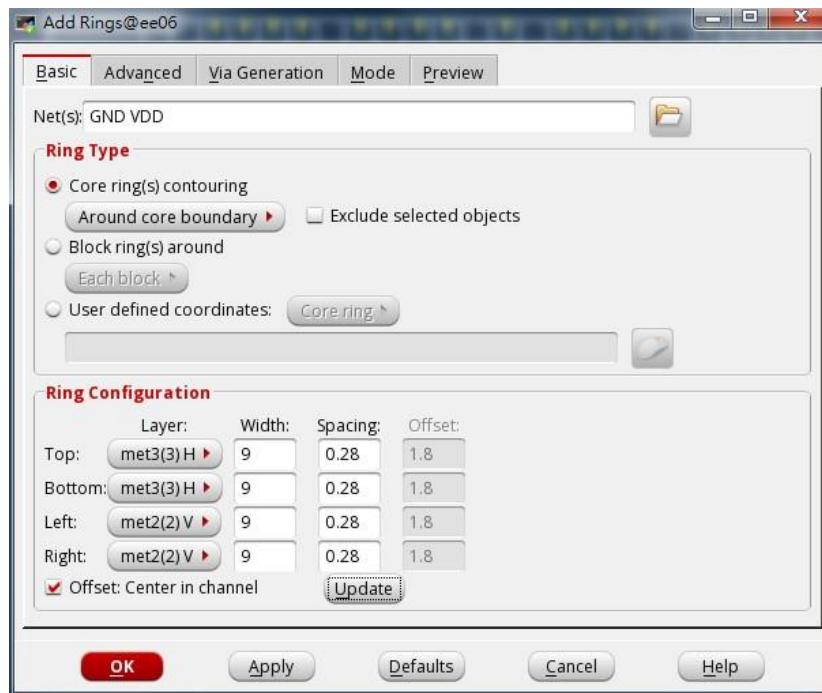
9. Apply the connection list and check:
 - e. Click **Apply** button
 - f. Click **Check** button
 - g. Click **Cancel** button

5. Power Planning (Add Core Power Rings)

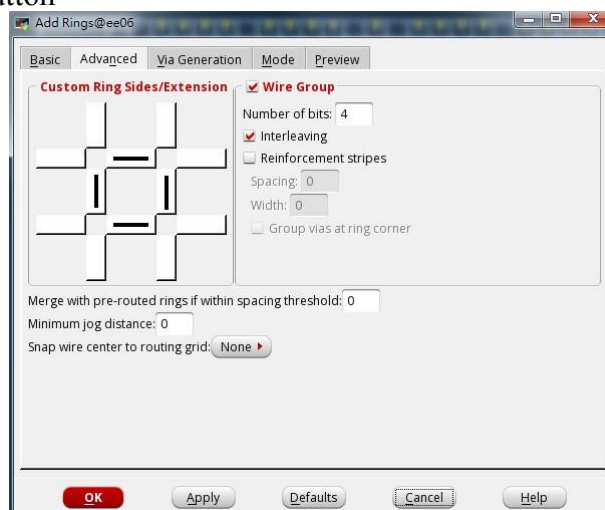
1. In innovus menu, open **Power** → **Power Planning** → **Add Rings...**




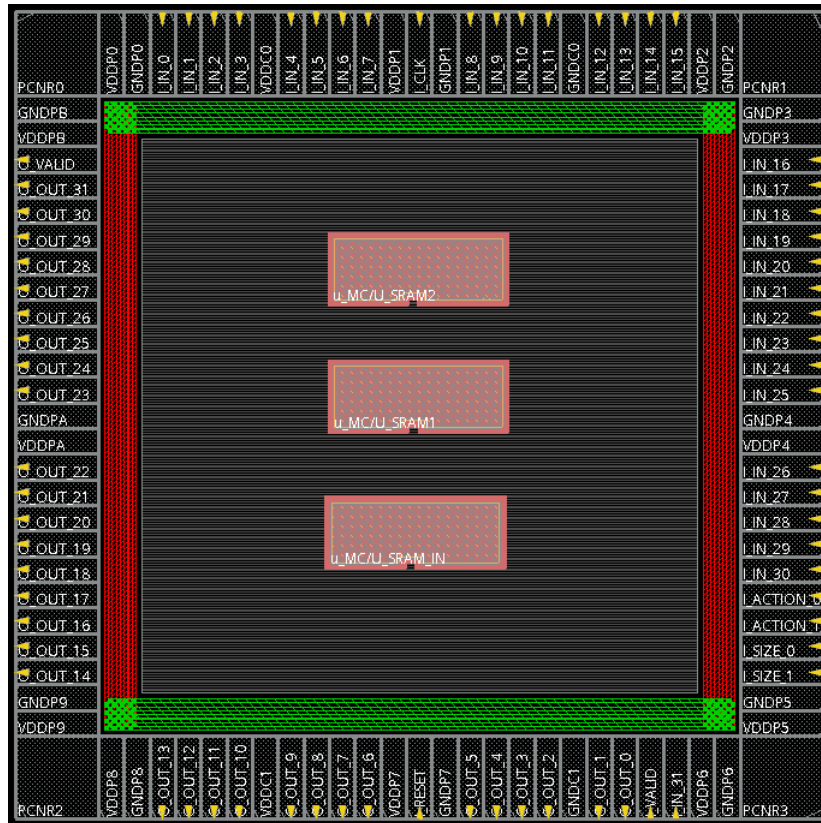
2. In the **Basic** tab, fill the following field:
 - a. Net(s): GND VDD
 - b. Ring Type: Core ring(s) contouring
 - c. Specify metal layers and width
 - Top Layer: **metal3 H** Width: **9**
 - Bottom Layer: **metal3 H** Width: **9**
 - Left Layer: **metal2 V** Width: **9**
 - Right Layer: **metal2 V** Width: **9**
 - ♦ Offset: Center in channel
 - Click **Update** button



3. In the **Advanced** tab, fill the following field:
 - a. ♦ Wire Group
 - b. Number of bits: 4
 - c. ♦ Interleaving
4. Click **OK** button

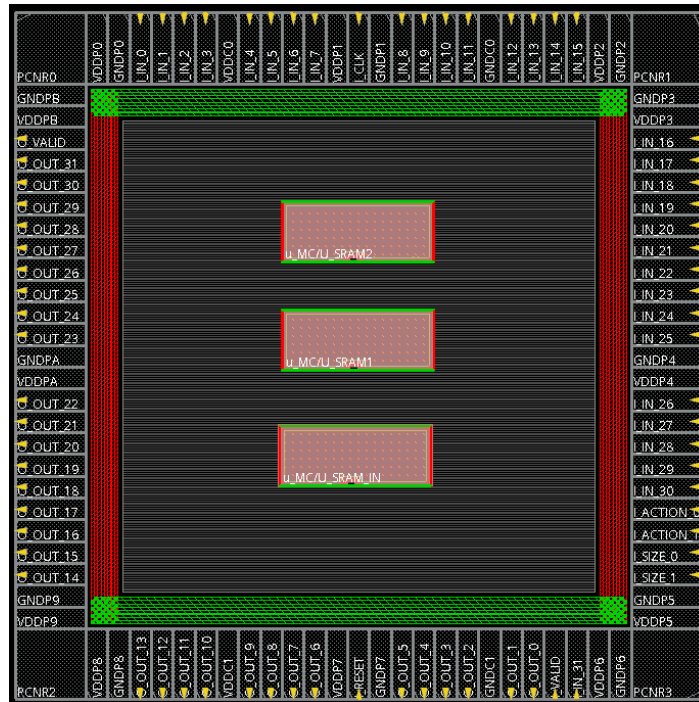


5. Check if the ring is correctly created. If not, click **undo** button  and repeat step 2~4 again.



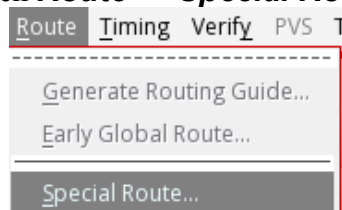
6. Power Planning (Add Block Rings)

1. In innovus menu, open **Power** → **Power Planning** → **Add Rings...**
2. In the **Basic** tab, fill the following field:
 - a. Net(s): GND VDD
 - b. Ring Type: Block ring(s) around
 - c. Specify metal layers and width
 - Top Layer: **met3(3) H** Width: 2
 - Bottom Layer: **met3(3) H** Width: 2
 - Left Layer: **met2(2) V** Width: 2
 - Right Layer: **met2(2) V** Width: 2
 - ◇ Offset: Center in channel
 - Click **Update** button
3. In the **Advanced** tab, disable the wire group:
 - a. ◇ Wire Group
4. Click **OK** button

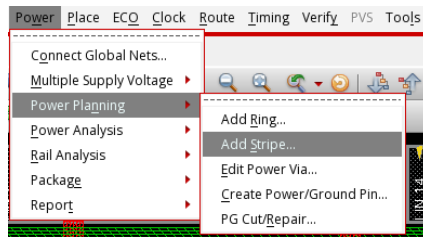


7. Connect Core Power Pin

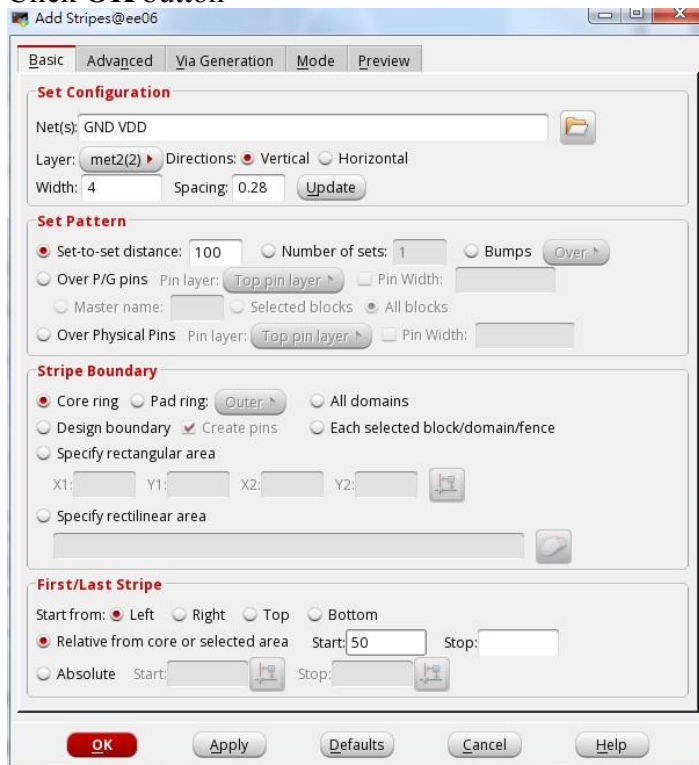
1. In innovus menu, open **Route** → **Special Route...**





2. Connect core power:
 - In **Basic** tab,
 - a. Net(s): GND VDD
 - b. Set the following configuration
SRoute:
 - ◇ Block pins
 - ◇ Pad rings
 - ◇ Floating Stripes
 - ◆ Pad pins
 - ◇ Follow pins
 - In **Via Generation** tab,
 - c. Set the following configuration
 - ◆ Core Ring
 - d. Click **OK** button

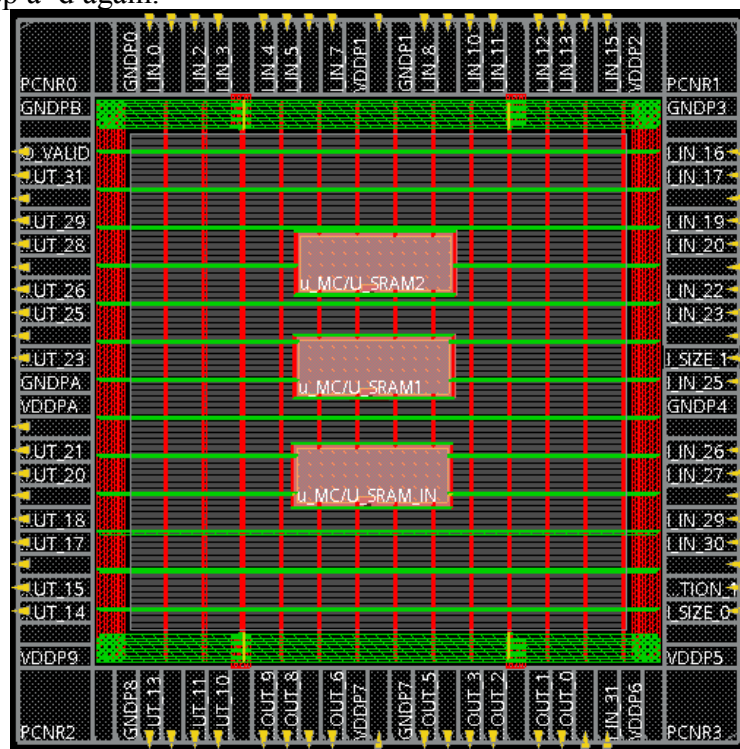


2. Create vertical power stripes:
 - a. Set Configuration
 - Net(s): GND VDD
 - Layer: **met2(2)**
 - Directions: **Vertical**
 - Width: **4**
 - Click **Update** Button
 - b. Set Pattern
 - **Set-to-set distance: 100**
 - c. First/Last Stripe
 - Start from: **Left**
 - **Relative from core or selected area**
 - Start: **50**
 - d. Click **OK** button



3. Check if the stripes are correctly created. If not, click **undo** button  and repeat step a~d again.
4. Create horizontal stripes:
 - a. Set Configuration
 - Net(s): GND VDD
 - Layer: **met3(3)**

- Directions: ♦ Horizontal
 - Width: 4
 - Click **Update** Button
 - b. Set Pattern
 - ♦ Set-to-set distance: **100**
 - c. First/Last Stripe
 - Start from: ♦ Bottom
 - ♦ Relative from core or selected area
 - Start: 50
 - d. Click **OK** button
5. Check if the stripes are correctly created. If not, click **undo** button  and repeat step a~d again.

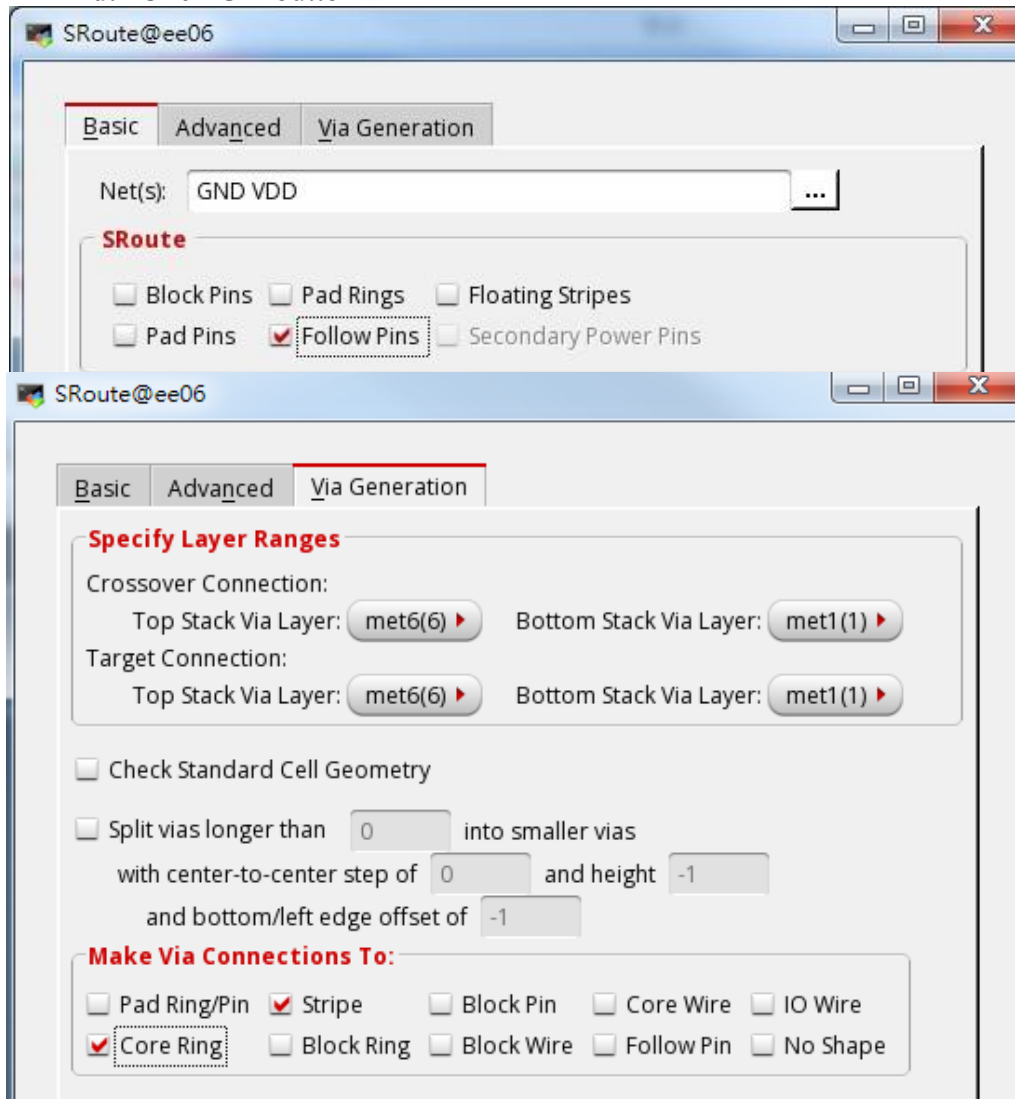


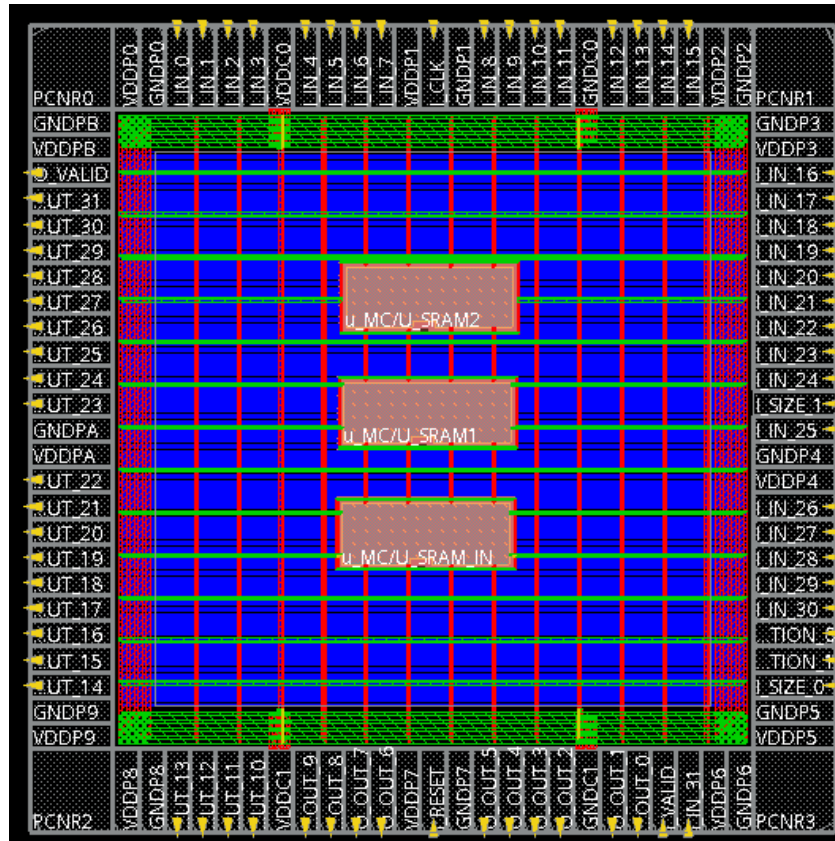
9. Connect Standard Cell Power Line

1. Make sure hard macro blockage has been added in floorplan.
2. In innovus menu, open **Route** → **Special Route...**
3. Connect core power:
 - In **Basic** tab,
 - a. Net(s): GND VDD
 - b. Set the following configuration
 - ◇ Block pins
 - ◇ Pad rings
 - ◇ Floating Stripes
 - ◇ Pad pins
 - ♦ Follow pins
 - In **Via Generation** tab,
 - c. Set the following configuration

- **◆ Stripe**
- **◆ Core Ring**

d. Click **OK** button





10. Verify DRC and LVS

1. In innovus menu, open **Verify** → **DRC**
 - Click **OK** button
 - Check routing for DRC error

Verification Complete : 0 Viols.

*** End Verify DRC (CPU: 0:00:00.3 ELAPSED TIME: 0.00 MEM: 1.0M) ***

Use **Tools** → **Violation Browser** to help finding Violations locations.

Ex.

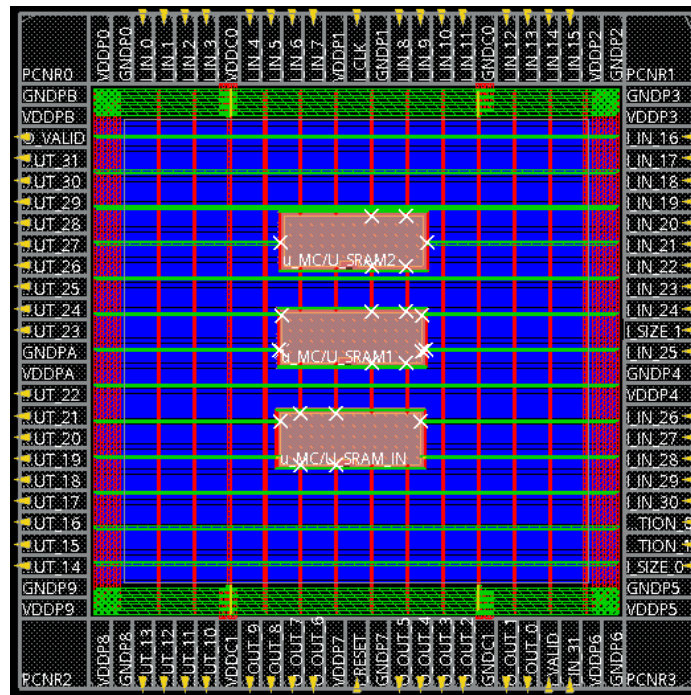
Cut_Short via4 → delete the via4 which make this violation

Cut_Spacing via4 → delete the via4 which make this violation

2. In innovus menu, open **Verify** → **Connectivity**
 - Net Type: ☒ Special Only
 - Nets: ☒ Named: GND VDD
 - Click **OK** button
 - Check routing for LVS error

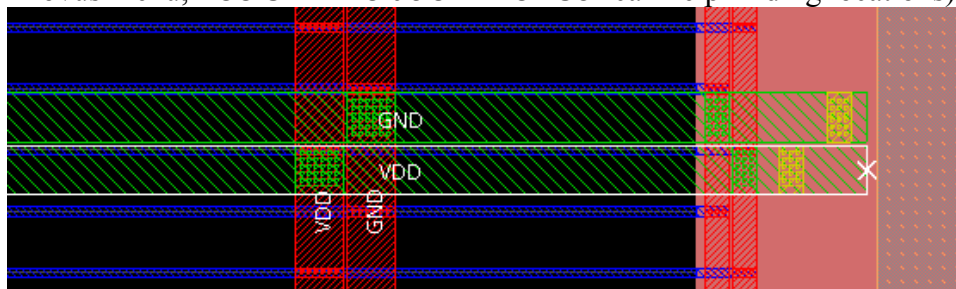


3. If the problem is the dangling wire (floating wire) around memory, like:

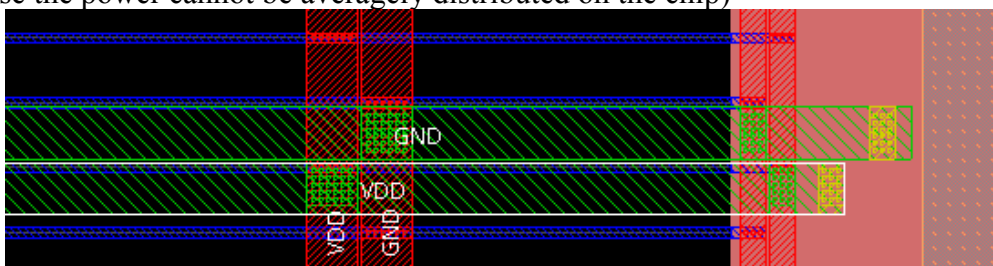


Zoom in and left click to select the highlighted wire:

(In innovus menu, **Tools** → **Violation Browser** can help finding locations)



Press “shift+t”, the dangling wire will be adjusted. (Do not delete those wires or else the power cannot be averagely distributed on the chip)



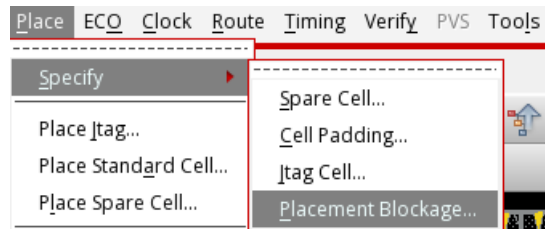
4. After fixing all the dangling wires, run step 2. Again to ensure the connectivity correctness.

```
***** End: VERIFY CONNECTIVITY *****
Verification Complete : 0 Viols. 0 Wrngs.
(CPU Time: 0:00:00.0 MEM: 0.000M)
```

5. Save design as CHIP_powerplan.inn

11. Place Standard Cells

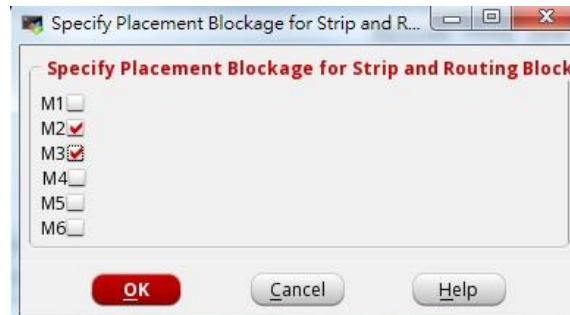
1. In innovus menu, open **Place** → **Specify** → **Placement Blockage**



2. Specify placement blockage for stripes
 - a. Specify placement blockage under metal2 and metal3

- ◇ M1
- ◆ M2
- ◆ M3
- ◇ M4
- ◇ M5
- ◇ M6

- b. Click **OK** button



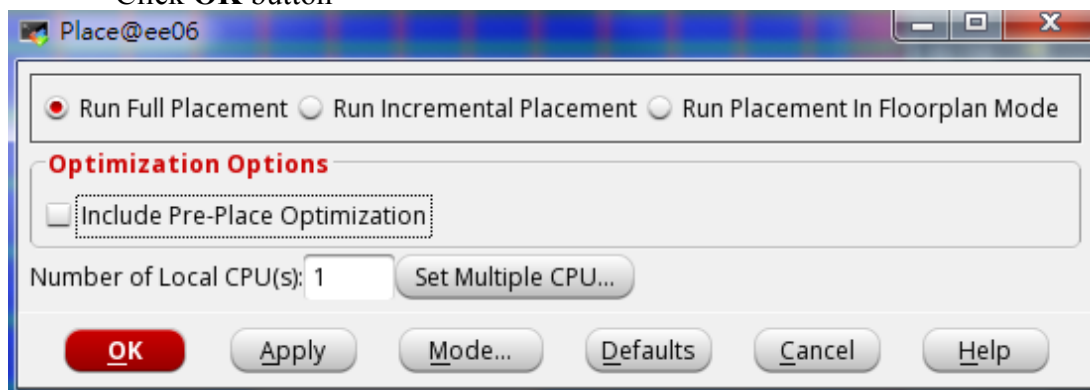
3. In innovus menu, open **Place** → **Place Standard Cells...**

- ◆ Run Full Placement

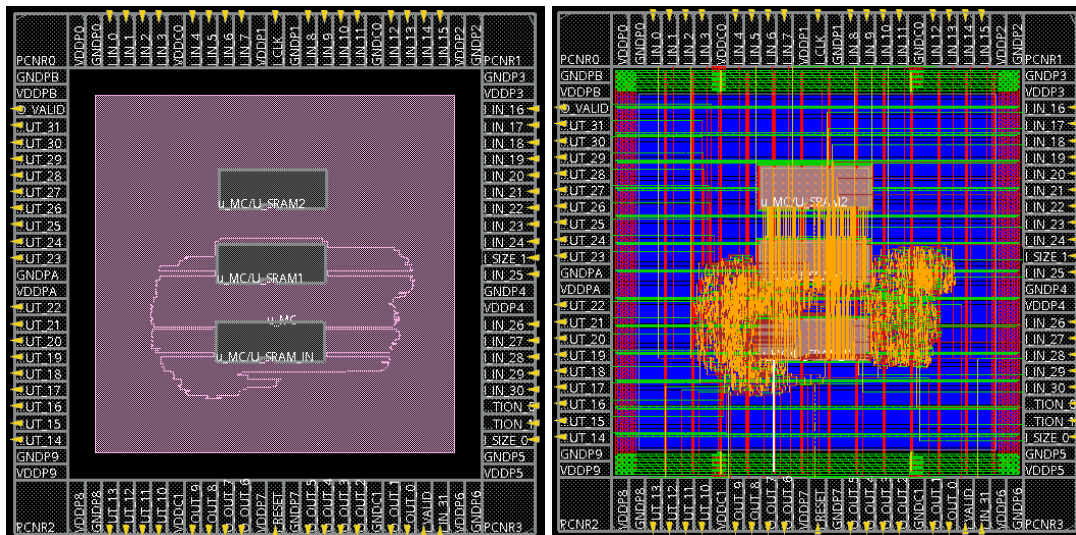
Optimization Options

- ◇ Include Pre-Place Optimization

Click **OK** button



The following figures show the results of Amoeba view and Physical view

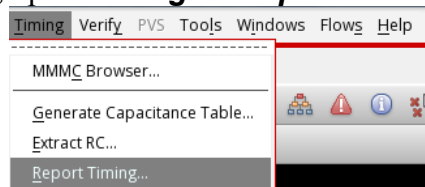


4. Save design as CHIP_placement.inn

12. In-Place Optimization (IPO)

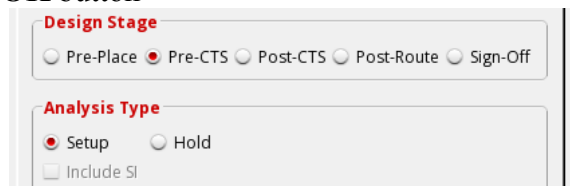
- Before Clock Tree Synthesis

1. In innovus menu, open **Timing** → **Report Timing...**

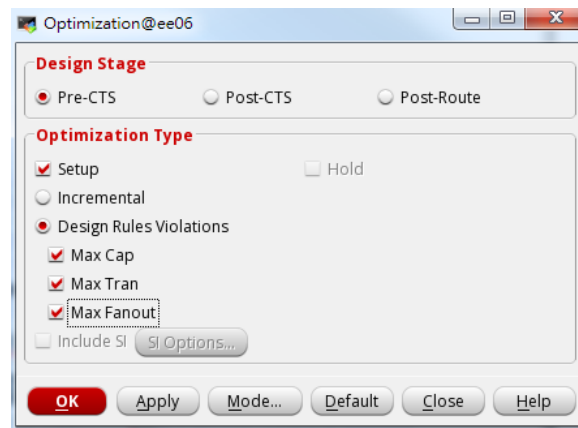


2. Perform trial route to model the interconnection RC effects

- a. Design Stage ♦ pre-CTS
- b. Analysis Type ♦ Setup
- c. Click OK button



3. See timing reports in **timingReports/** directory, **CHIP_preCTS.slk** shows the timing analysis results. All slack values must be positive value in this file. Moreover, for detail path report, see **CHIP_preCTS_all.tarpt**. DRVs report files: ***.cap**, ***.fanout**, and ***.tran**.
4. If the timing slack is negative, or there are DRVs, open **ECO** → **Optimize Design...** in innovus menu
5. Perform pre-CTS IPO
 - a. Design Stage ♦ Pre-CTS
 - b. Optimization Type
 - ♦ Setup
 - ♦ Design Rule Violations
 - ♦ Max Cap
 - ♦ Max Tran
 - ♦ Max Fanout
 - c. Click **OK** button



6. Save design as CHIP_preCTS.inn

In preCTS timing report, the max cap violation of DRV may be caused by reset_n or clk, which connects to a lot of registers. After ECO, the rst_n DRV may be fixed by inserting buffers. Whereas the clk may not since the clk buffers will be inserted in the next step: Clock Tree Synthesis (CTS) stage. The remaining clk DRV will be shown like:

DRVs	Real		Total
	Nr nets(terms)	Worst Vio	Nr nets(terms)
max_cap	0 (0)	0.000	1 (1)
max_tran	0 (0)	0.000	0 (0)
max_fanout	0 (0)	0	0 (0)
max_length	0 (0)	0	0 (0)

and can be view in the file *timingReports/CHIP_preCTS.tran.gz*. This DRV should be fixed after synthesizing the clock tree, thus don't worry in this stage. You only have to worry if this DRV cannot be fixed after CTS.

You will also see **Density** and **Routing Overflow** terms at the bottom of the timing report.

```
Density: 8.473%
Routing Overflow: 0.00% H and 0.00% V
```

The lower the density is, the lower the standard cells (excluding Hardmacros) are utilizing the core, which means it provides larger flexibility in further routing and optimization steps.

After the placement and in the preCTS stages, innovus performs **trial route** to give the rough delay calculation of path between every registers / input output ports so the preCTS can be done. Similar to the density which is the placement utilization, the routing overflow represents the wiring congestion level. The higher the routing overflow is, the harder of the coming CTS and detail routing (**nanoroute**). Usually when Horizontal and Vertical routing overflow are both < 0.5% ~ 1.0%, the further routing problem will be small. The routing overflow term will disappear after **nanorouting** since the **detail route** will be given to replace the **trial route**.

13. Clock Tree Synthesis (CTS)

- Set updated latency false
 - innovus > set_ccopt_property update_io_latency false
- Create clock tree specification file from the SDC constraints:
 - innovus > create_ccopt_clock_tree_spec -file CHIP.CCOPT.spec -keep_all_sdc_clocks

3. Load clock tree specification and synthesize clock tree
 - innovus > source CHIP.CCOPT.spec
 - innovus > ccopt_design

4. Save design as CHIP_CTS.inn

14. In-Place Optimization (IPO)

- After Clock Tree Synthesis

1. In innovus menu, open **Timing** → **Report Timing...**
2. Perform trial route to model the interconnection RC effects
 - a. Design Stage ♦ Post-CTS
 - b. Analysis Type ♦ Setup
 - c. Click **OK** button
3. See timing reports in **timingReports/** directory, **CHIP_postCTS.slk** shows the timing analysis results. All slack values must be positive value in this file. Moreover, for detail path report, see **CHIP_postCTS_all.tarpt**. DRVs report files: ***.cap**, ***.fanout**, and ***.tran**.
4. If the timing slack is negative, or there are DRVs, open **ECO** → **Optimize Design...** in innovus menu
5. Perform post-CTS IPO
 - a. Design Stage ♦ Post-CTS
 - b. Optimization Type
 - ♦ Setup
 - ♦ Design Rule Violations
 - ♦ Max Cap
 - ♦ Max Tran
 - ♦ Max Fanout
 - c. Click **OK** button

From post CTS steps, hold time checking is also required

6. In innovus menu, open **Timing** → **Report Timing...**
7. Perform trial route to model the interconnection RC effects
 - a. Design Stage ♦ Post-CTS
 - b. Analysis Type ♦ Hold
 - c. Click **OK** button
8. See timing reports in **timingReports/** directory, **CHIP_postCTS_hold.slk** shows the timing analysis results. All slack values must be positive value in this file. Moreover, for detail path report, see **CHIP_postCTS_all_hold.tarpt**. DRVs report files: ***.cap**, ***.fanout**, and ***.tran**.
9. If the timing slack is negative, or there are DRVs, open **ECO** → **Optimize Design...** in innovus menu
10. Perform Post-CTS IPO
 - a. Design Stage ♦ Post-CTS
 - b. Optimization Type
 - ♦ Hold
 - ♦ Design Rule Violations
 - ♦ Max Cap
 - ♦ Max Tran

◆ Max Fanout

c. Click **OK** button

11. Save design as CHIP_postCTS.inn

15. Add PAD Filler

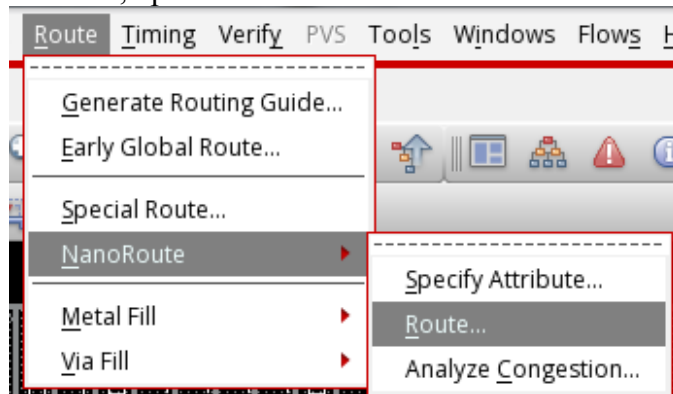
1. In innovus command prompt, execute the following commands:

- **addIoFiller -cell PFILL -prefix IOFILLER**
- **addIoFiller -cell PFILL_9 -prefix IOFILLER**
- **addIoFiller -cell PFILL_1 -prefix IOFILLER**
- **addIoFiller -cell PFILL_01 -prefix IOFILLER -fillAnyGap**

PAD filler must be added before detail route, or there may have some DRC/LVS violations after PAD filler insertion

16. SI-Prevention Detail Route (NanoRoute)

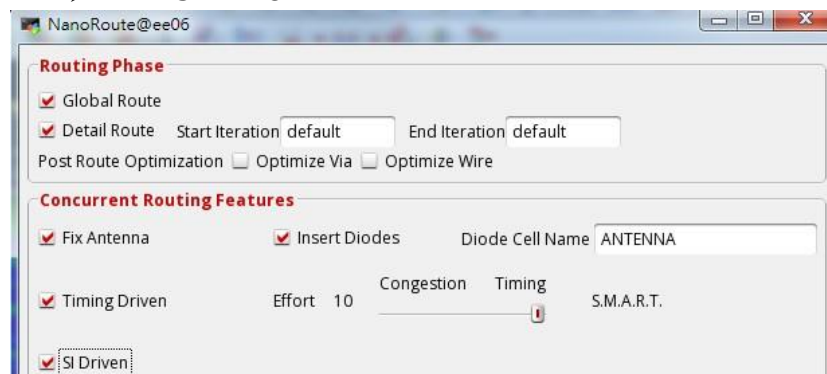
1. In innovus menu, open **Route** → **NanoRoute** → **Route**



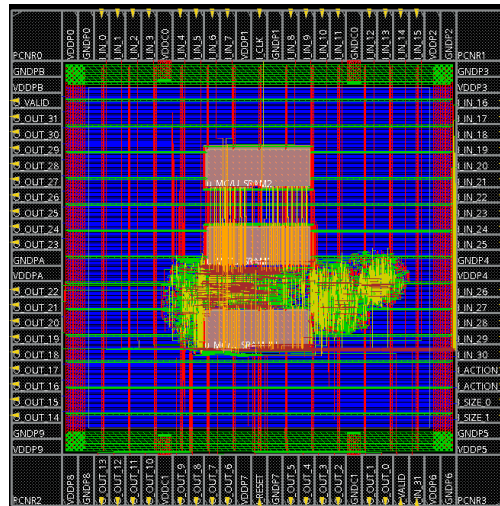
2. Nanoroute can prevent cross talk effects and fix antenna rule violations, also it routes design to meet timing constraints.

a. Configure routing features

- ◆ Fix Antenna
- ◆ Insert Diodes Diode Cell Name: ANTENNA
- ◆ Timing Driven Effort: 10
- ◆ SI Driven

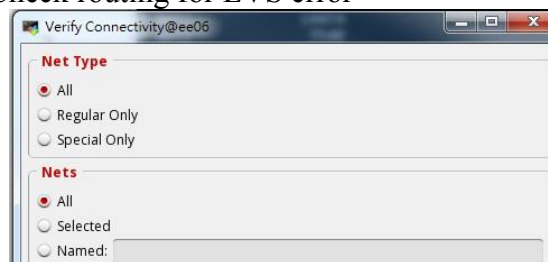


b. Click **OK** button



3. In innovus menu, open **Verify** → **Connectivity**

- Net Type: ☒ All
- Nets: ☒ All
- Click **OK** button
- Check routing for LVS error



4. In innovus menu, open **Verify** → **DRC**

- Click **OK** button
- Check routing for DRC error

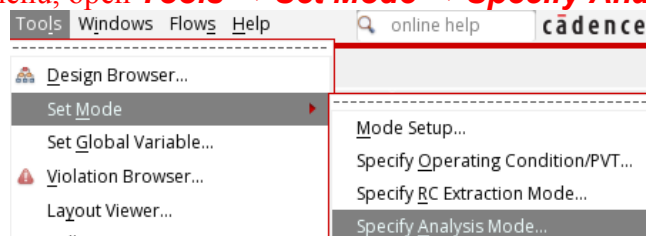
```
Verification Complete : 0 Viols.
*** End Verify DRC (CPU: 0:00:00.3 ELAPSED TIME: 0.00 MEM: 1.0M) ***
```

5. Save design as CHIP_nanoRoute.inn

17. In-Place Optimization (consider crosstalk effects)

- After Detail Route

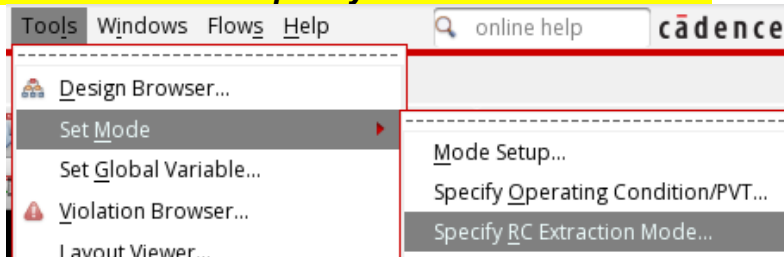
1. In innovus menu, open **Tools** → **Set Mode** → **Specify Analysis Mode...**



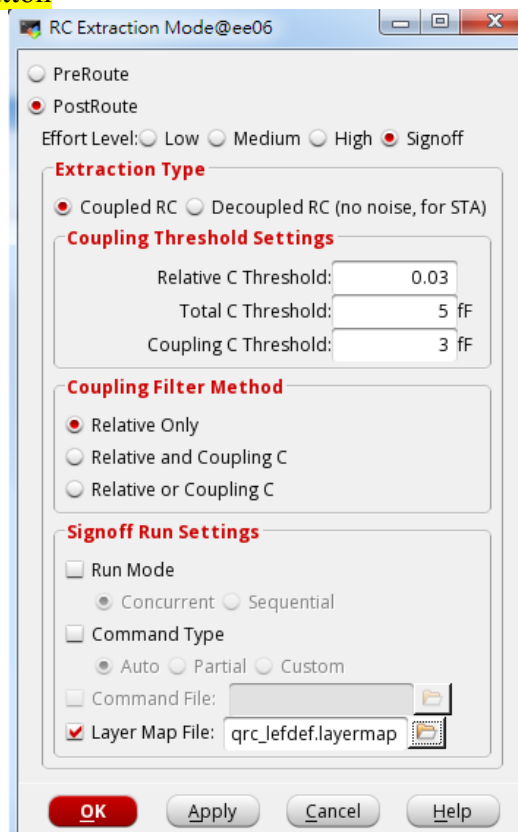
- a. Timing Mode: ☒ On-Chip Variation
- b. Click **OK** button



2. In innovus menu, open **Tools** → **Set Mode** → **Specify RC Extraction Mode...**



- a. ♦ **PostRoute**
- b. Effort Level: ♦ **Signoff**
- c. Extraction Type: ♦ **Coupled RC**
- d. Signoff Run Settings:
- ♦ Layer Map File: **qrc_lefdef.layermap**
- e. Click **OK** button



3. Setting rc and si
 - innovus > set_db extract_rc_engine post_route
 - innovus > set_db extract_rc_effort_level high
 - innovus > set_db delaycal_enable_si true
4. In innovus menu, open **Timing** → **Report Timing...**
5. Perform trial route to model the interconnection RC effects
 - a. Design Stage ♦ **Post-Route**
 - b. Analysis Type ♦ **Setup**
 - c. Click **OK** button

6. See timing reports in **timingReports/** directory, **CHIP_postRoute.slk** shows the timing analysis results. All slack values must be positive value in this file. Moreover, for detail path report, see **CHIP_postRoute_all.tarpt**. DRVs report files: ***.cap**, ***.fanout**, and ***.tran**.
7. If the timing slack is negative, or there are DRVs, open **ECO→Optimize Design...** in innovus menu
8. Perform post-Route IPO
 - a. Design Stage ◆ post-Route
 - b. Optimization Type
 - ◆ Setup
 - ◆ Design Rule Violations
 - ◆ Max Cap
 - ◆ Max Tran
 - ◆ Max Fanout
 - c. Click **OK** button
9. In innovus menu, open **Timing → Report Timing...**
10. Perform trial route to model the interconnection RC effects
 - a. Design Stage ◆ Post-Route
 - b. Analysis Type ◆ Hold
 - c. Click **OK** button
11. See timing reports in **timingReports/** directory, **CHIP_postRoute_hold.slk** shows the timing analysis results. All slack values must be positive value in this file. Moreover, for detail path report, see **CHIP_postRoute_all_hold.tarpt**. DRVs report files: ***.cap**, ***.fanout**, and ***.tran**.
12. If the timing slack is negative, or there are DRVs, open **ECO→Optimize Design...** in innovus menu
13. Perform post-Route IPO
 - a. Design Stage ◆ post-Route
 - b. Optimization Type
 - ◆ Hold
 - ◆ Design Rule Violations
 - ◆ Max Cap
 - ◆ Max Tran
 - ◆ Max Fanout
 - c. Click **OK** button
14. Save design as **CHIP_postRoute.inn**

18. Timing Analysis (Signoff)

- Optional in this Practice

Signoff timing analysis is similar to postRoute timing analysis. In addition to invoke Quantus QRC Extraction tool to calculate the RC delay as postRoute, **it also consider the SI affect with the signoff RC**.

Currently, the delay considering the SI affect with signoff RC can be only used for timing analysis, but cannot be used for timing optimization. If you want to perform timing analysis or timing optimization for postRoute again after signoff timing analysis, you need to reset the SI mode by the command: **innovus > setDelayCalMode -siMode signoff**

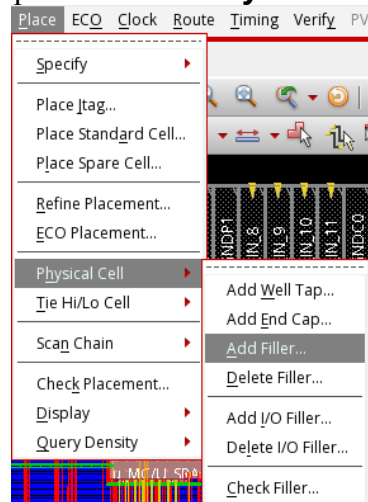
1. In innovus menu, open **Timing → Report Timing...**
2. Perform trial route to model the interconnection RC effects

- a. **Design Stage ♦ Sign-Off**
 - b. Analysis Type ♦ Setup
 - c. Click **OK** button
3. See timing reports in **timingReports/** directory, **CHIP_signOff.slk** shows the timing analysis results. All slack values must be positive value in this file. Moreover, for detail path report, see **CHIP_signOff_all.tarpt**. DRV's report files: *.cap, *.fanout, and *.tran.
4. In innovus menu, open **Timing → Report Timing...**
5. Perform trial route to model the interconnection RC effects
 - a. **Design Stage ♦ Sign-Off**
 - b. Analysis Type ♦ Hold
 - c. Click **OK** button
6. See timing reports in **timingReports/** directory, **CHIP_signOff_hold.slk** shows the timing analysis results. All slack values must be positive value in this file. Moreover, for detail path report, see **CHIP_signOff_all_hold.tarpt**. DRV's report files: *.cap, *.fanout, and *.tran.

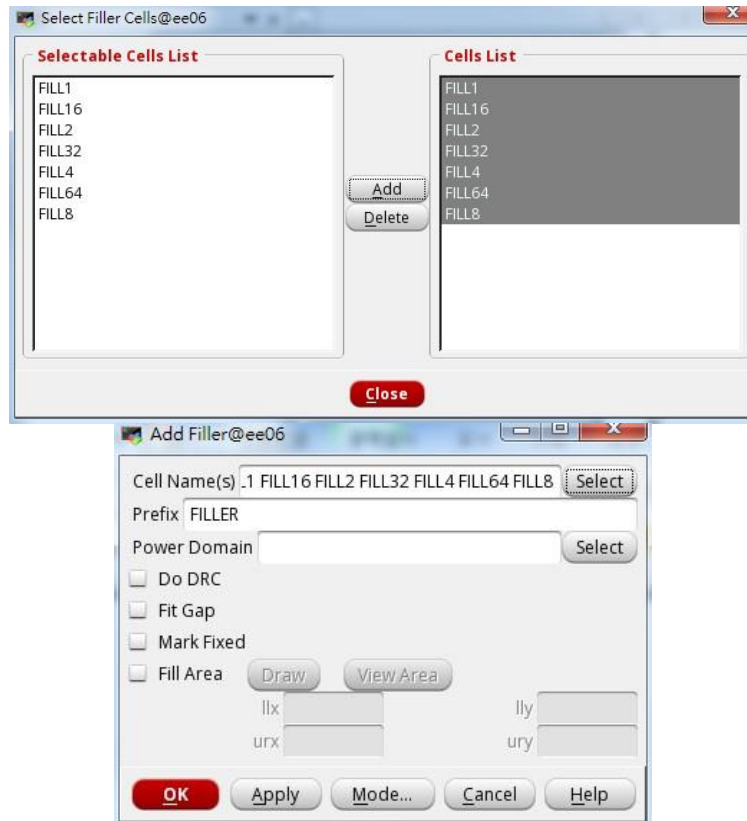
You can perform the above steps to see if there is any difference between the results between the signoff timing analysis and the postRoute timing analysis. **In most experiences and in this practice, signoff timing analysis result is very closed the postRoute timing analysis.** Thus in this practice you can choose to perform this step or not.

19. Add CORE Filler Cells

1. In innovus menu, open **Place → Physical Cell → Add Filler**



2. Add core filler to improve electric effects of NWELL and PWELL:
 - a. Click **Select** button next to Cell Name(s)
 - b. Select all core filler cells
 - c. Click **Add** button
 - d. Click **Close** button
 - e. Click **OK** button



20. Stream Out and Write Netlist

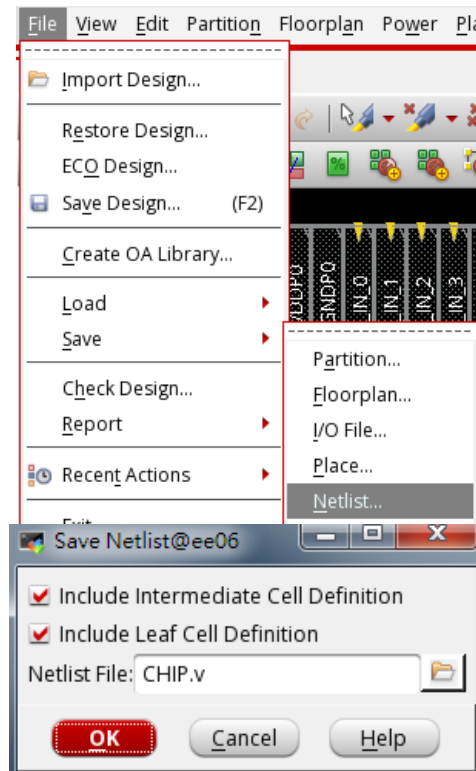
1. Save design as **CHIP.inn**
2. Write CHIP.sdf
 - a. In innovus menu, open **Timing** → **Write SDF**
 - b. Delay Calculation Option
 - ◇ Ideal Clock

Ideal Clock should be disabled
 - c. Click **OK** button



(or you can use the command “write_sdf CHIP.sdf”)

3. Save design netlist CHIP.v for post-layout simulation:
 - a. In innovus menu, open **File** → **Save** → **Netlist...**
 - ◆ Include Intermediate Cell Definition
 - ◆ Include Leaf Cell Definition
 - Netlist File: **CHIP.v**
 - Click **OK** button



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21. Post-Layout Gate-Level Simulation

1. Change to directory **06_POST**
2. Perform Post-Layout Gate-level simulation of CHIP.v
% ./01_run The latency should be the same as gate level simulation

Appendix: IO Pad assignment

CHIP.io:

Pad: T1 N
Pad: T2 N

Pad: R2 E
Pad: R3 E PFILL # If this pad is a pad filler

Pad: B2 S
Pad: B3 S

Pad: L1 W
Pad: L2 W

Pad: C1 SW PCORNER Pad:
C2 NW PCORNER Pad: C3
NE PCORNER Pad: C4 SE
PCORNER

